World Literature Review

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Review Covers Recent Issues of Galvanotechnik, Metalloberfläche, Transactions of the IMF & Hyomen Gijutsu

Metalloberfläche

August 1998

Cleaning & Pretreatment

"Opportunities for Optimizing the Use of Grinding Belts," W. Heidtmann
"Blasting with CO_2 Dry Ice," A. Visser, J. Haberland & F-H. Budde

Plating & Alternative Processes

"Anodizing Process Control," T. Korner
"Deposition of Cobalt," I. Krastev, N. Petkova & A. Zielonka
"NiP Dispersion-hardened Coatings," E. Dobreva & C. Petrov
"Tribology of Solid Lubricant Films," W. Scheerer & F. Dürr

September 1998

Plating & Alternative Processes

"Electrophoretic Clear Varnishing for Decorative Surface Treatments," U. Berger
"Bronze & Hard Bronze Coatings," K. Wilbuer & H.H. Urlberger
"Tribological Coatings," J. Brand
"Transparent, Scratch-resistant Coatings," R. Hartmann & C. Laubner

Painting & Powder Coating

"Automatic Powder Coating," B. Lutz
"Efficient Contract Painters Favor Powder Coating," T. Bertow
"Colors A-plenty"

Galvanotechnik

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Plating & Alternative Processes

"Studies on the Corrosion Behavior of Magnesium after Oxygen Ion Implantation," M. Schneider, K. Nocke & E. Richter
"Non-destructive & Contactless Characterization of Coatings Using Microwaves," C. Sklarczyk
"Internal Coating of Aluminum Cylinder Bores Using PVD, Part 2," E. Lugscheider & Ch. Wolff
"Rinsing: Theoretical Basis & Calculations for Rinsing Systems, Part 5—Calculations of Change of Concentration During a Rinse Cycle," C. Kubik

Printed Circuit Board Technology

"Organic Circuit Board Substrates with Solder Deposits for Flip-Chip Assembly," W.J. Malwald
"Organic Metals: A New Class of Material for Electronics, Corrosion Protections & ..., Part 2—A Revolutionary, Efficient Corrosion Protection Technology," B. Wessling
"Wire Bonding: What is Bondability?" L. Berchtold

Waste Treatment & Recycling

"Recycling of Sludges from Vibratory Finishing & Spent Media or Chips," V. Löhnert
"Prevention in Electroplating, Part 4," H. Felike

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Plating & Alternative Processes

"Process for the Deposition of Metallic Coatings," N. Kanani
"Effect of Alloying Elements on the Formation, Adhesion & Corrosion Protection of Chromate Coatings Used in the Chemical Pretreatment of Aluminum," Ch. Nachtmann
"Effect of Nickel Chloride on Anode Solubility, Hardness & Internal Stress in Thick Nickel Films Formed from Sulphamate Electrolytes: Initial Results with a Chloride-free Electrolyte," E. Kranz
"A Comparison of HVOF Systems: Behavior of Materials & Coating Properties," H. Kreye
"Organic Metals: A New Class of Material for Electronics, Corrosion Protections & ..., Part 3—A Finish Revolution: Organic Metal plus Electroless Tin," B. Wessling
"Rinsing: Theoretical Basis & Calculations for Rinsing Systems, Part 6—Concentration Increases in Counterflow Rinsing Systems" C. Kubik

Transactions of the Institute of Metal Finishing

September 1998 • Vol. 76, Part 5

Plating & Alternative Processes

"Alternatives to Electroplated Cad-

"mium," M.B. Sunthankar & S.D. Joshi

"The Future for Electroplating of Electromagnetic Materials in Micro-electronics," J.-P. Celis, P. Cavallotti, J. Machado de Silva & A. Zielonka

"Experience with a Pilot Plant for the Electrodeposition of Zn-Mn on Wire," B. Bozzini, F. Pavan & P. Cavallotti

"The Effects of Molybdate Ions on a.c. Sulphuric Acid Anodized 6063 Aluminum Alloys," F. Sertçelik, A.F. Çakir, M. Ürgen, D.H. Ross & D.R. Gabe

"Plasma-sprayed PMMA Coatings on Steel," T. Zhang, D.T. Gawne & Y. Bao

"A Study on Zinc-Iron Alloy Electrodeposition from a Chloride Electrolyte," J.D. Jensen, G.W. Critchlow & D.R. Gabe

"Effect of Superimposed Sinusoidal a.c. on the Characteristics of Electrodeposited Ni, Cu & Cu-Ni Alloy Composites with α-Al_2O_3 and TiO_2," M.H. Fawzy, M.M. Ashour & A.M. Abd El-Halim

"The Effectiveness of TEA CO_2-laser Ablation for the Treatment of Hot-dipped Galvanized Mild Steel Prior to Adhesive Bonding," G.W. Critchlow, K.H. Bedwell & C.A. Cottam

"Influence of Deposition Current Density on the Magnetization Behavior in Electrodeposited Ni-Mn Alloys," M.V. Ananth

`Hyomen Gijutsu`

October 1998 • Vol. 49, No. 10

Plating & Alternative Processes

"Wet Etching—Theory & Application," K. Kato

"Control of Bath for Engineering Cr Plating & Its Effects," H. Abe

"Surface Analysis of Surface-treated Steel Sheets," S. Maeda

"Surface Finishing on Glass (Hydrophilic & Hydrophobic Treatment)," K. Okuno

"Coating Layer Modification in Zn-Al Hot-dipped Steel Bolts," J. Tanaka, M. Sakaguchi & T. Narita

"The Structure of Poly-molybdate Ions & Its Relevance to the Electroplating of Molybdenum Alloy," K. Shinoda, E. Matsubara, y. Waseda, E. Uekawa, K. Murase, T. Hirato & Y. Awakura

"Anomalous Deterioration of IrO_2-based Anodes by Periodically Reversed Electrolysis," H. Meng, M. Morimitsu & M. Matsunaga

"Preparation of Ultra-fine Pattern Formation by Electro Copper Plating," J. Ishibashi, Y. Takada & H. Honma

"Electrodeposition of Zinc on Thermal Electrode," H. Liu & M. Okido

Printed Circuit Board Technology

"Technical Trend on Etching for High-density Printed Wiring Boards," M. Toyonaga

"Etching Technology for Various Plastics," K. Sato

"Etching of Various Plated Metal Film," Y. Tsukui

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Metalloberfläche	**011-49-75 81-1756**
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Trans. of the IMF	**011-44-0121-666-6316**

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